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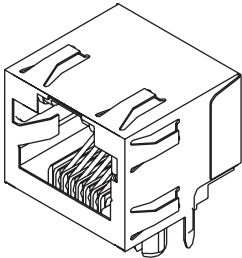
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Jameco Part Number 1931974

Modular Jack

43860

Right Angle, Low Profile, Inverted
Shielded and Unshielded Versions



Features and Benefits

- Plug latch on top
- Shortened leads with bottom contacts
- Shielding meets IEC 950, UL 1863 and CSA 233
- Enhanced panel grounding tabs on shield
- 100% tested for hi-pot and continuity

Reference Information

Product Specification: PS-43860-003
Packaging:
Unshielded—Tube
Shielded—Tray
UL File No.: E107635
CSA File No.: LR19980
Mates With: FCC 68 plugs
Designed In: Inches

Electrical

Voltage: 125V
Current: 1.5A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 1000V AC
Insulation Resistance: 500 Megohms min.

Mechanical

Durability: 500 cycles min.

Physical

Housing: Black glass-filled nylon, UL 94V-0
Contact: Phosphor Bronze
Plating: Contact Area—1.27µm (50µ") min. Gold;
Solder Tails—2.54µm (100µ") min. Tin,
Nickel overall
Operating Temperature: -40 to +80°C

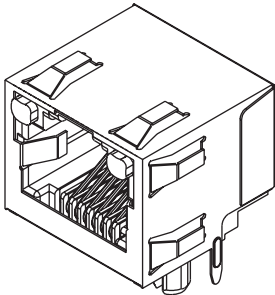
Circuits	Loaded Contacts	Order No.			Lead-free
		Unshielded	Shielded		
			With All Panel Grounding Tabs	With Offset Panel Grounding Tabs	
6	2	43860-0020	43860-0024		Yes
	4	43860-0003	43860-0006	43860-0015	
	6	43860-0002	43860-0005	43860-0014	
8	8	43860-0001	43860-0004	43860-0013	

Note: Visit www.molex.com for additional panel grounding tab options

Modular Jack

43860

Right Angle, Low Profile, Inverted Shielded and Unshielded Versions With Lightpipes



- Features and Benefits**
- Plug latch on top
 - Shortened leads with bottom contacts
 - Industry compatible
 - Lower electrical noise than LED offerings
 - 34% fewer leads than LED offerings
 - Enhanced grounding tabs on shield

Reference Information
 Product Specification: PS-43860-003
 Packaging:
 Unshielded—Tube
 Shielded—Tray
 UL File No.: E107635
 CSA File No.: LR19980
 Designed in: Inches

Electrical
 Electrical Voltage: 125V
 Current: 1.5A max.
 Contact Resistance: 20 milliohms max.
 Dielectric Withstanding Voltage: 1000V AC
 Insulation Resistance: 500 Megohms min.

Mechanical
 Durability: 500 cycles

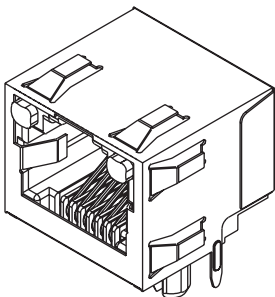
Physical
 Housing: Black glass-filled nylon, UL 94V-0
 Plating: Contact Area—1.27µm (50µ") min. Gold
 Solder Tails—2.54µm (100µ") min. Tin,
 Nickel overall
 Operating Temperature: -40 to +80°C

Circuits	Loaded Contacts	Order No.			Lead-free
		Unshielded	Shielded		
			With All Panel Grounding Tabs	With Offset Panel Grounding Tabs	
6	4	43860-0009	43860-0012	43860-0018	Yes
6	6	43860-0008	43860-0011	43860-0017	
8	8	43860-0007	43860-0010	43860-0016	

Modular Jack

43860

Right Angle, Low Profile Inverted, Shielded Version With High Temperature* Lightpipes



- Features and Benefits**
- Plug latch on top
 - Lower electrical noise than LED offerings
 - 34% fewer leads than LED offerings
 - Enhanced grounding tabs on shield

Reference Information
 Product Specification: PS-43860-003
 Packaging: Tray
 UL File No.: E107635
 CSA File No.: LR19980
 Designed in: Inches

Electrical
 Electrical Voltage: 125V
 Current: 1.5A max.
 Contact Resistance: 20 milliohms max.
 Dielectric Withstanding Voltage: 1000V AC
 Insulation Resistance: 500 Megohms min.

Mechanical
 Durability: 500 cycles

Physical
 Housing: Black glass-filled nylon, UL 94V-0
 Contact: Phosphor Bronze
 Plating: Contact Area—1.27µm (50µ") min. Gold
 Solder Tails—2.54µm (100µ") min. Tin,
 Nickel overall
 Operating Temperature: -40 to +80°C

Circuits	Loaded Contacts	Order No.		Lead-free
		With All Panel Grounding Tabs	With Offset Panel Grounding Tabs	
6	4	43860-1012	43860-1018	Yes
	6	43860-1011	43860-1017	
8	8	43860-1010	43860-1016	

*Reflow capable up to 205°C for 30 seconds max.



PRODUCT SPECIFICATION

INVERTED RIGHT ANGLE MODULAR JACKS

1.0 SCOPE

This Product Specification covers the 1.02 mm (.040 inch) centerline (pitch) printed circuit board (PCB) modular jack connector series with selective gold and tin plating.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Single Port Inverted Modular Jack	43860
Single Port Inverted Mini-PCI Modular Jack	44380
Dual Port Inverted Modular Jack	43814
Ganged Inverted Modular Jack	44248
Single Port Inverted Modular Jack with Keep-out Feature	44620

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate sales drawings (SD-43860-001, SD-44380-001, SD-43814-001, SD-44248-001) for information on dimensions, materials, plating and markings.

2.3 SAFETY AGENCY APPROVALS

UL File Number.....E107635
CSA File Number.....LR19980

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

FCC Rules and Regulations, Part 68, Subpart F
REA Bulletin 345-81, PE-76; Specification for modular telephone set hardware
ANSI/EIA/TIA-568
IEC-60603-7
UL 1863
MIL-STD-202; General requirements for test specifications

4.0 RATINGS

4.1 VOLTAGE

56.5 V DC
150 V_{RMS} AC (Ringing voltage only)

4.2 CURRENT

1.5 Amps @ 25°C

4.3 TEMPERATURE

Operating: - 40°C to + 85°C
Nonoperating:* - 40°C to + 85°C
*Packaging materials should not exceed + 50°C

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
H2	EC No: UCP2008-0143 DATE: 7/23/2007	PRODUCT SPECIFICATION INVERTED RIGHT ANGLE MODULAR JACKS	1 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43860-003	JBELL 7/23/2007	LSCHMIDT 7/24/2007	FSMITH 7/25/2007



PRODUCT SPECIFICATION

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA. (Measurement locations in Section 7.0)	20 milliohms MAXIMUM [initial]
	Insulation Resistance	Unmated connector, mounted to a PCB: apply a voltage of 100 VDC between adjacent terminals and between terminals to ground.	500 Megohms MINIMUM
	Dielectric Withstanding Voltage	Mate connectors: apply a voltage of 1000 VAC for 1 minute between adjacent terminals and between terminals to ground.	No breakdown; current leakage < 5 mA

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
H2	EC No: UCP2008-0143 DATE: 7/23/2007	PRODUCT SPECIFICATION INVERTED RIGHT ANGLE MODULAR JACKS	2 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43860-003	JBELL 7/23/2007	LSCHMIDT 7/24/2007	FSMITH 7/25/2007



PRODUCT SPECIFICATION

5.2 MECHANICAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Connector Mate Force	Mate connector at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute. (Gage dimensions in Section 7.0)	22 N (5 lbf) unshielded MAXIMUM insertion force 35 N (8 lbf) shielded MAXIMUM insertion force
	Durability	Mate connectors up to 500 cycles at a maximum rate of 10 cycles per minute prior to Environmental Tests.	10 milliohms MAXIMUM (change from initial)
	Vibration (Random)	Amplitude: 1.50mm (.060") peak to peak Sweep: 10-55-10 Hz in one minute Duration: 15 minutes ±X,±Y,±Z axis (45 minutes total)	10 milliohms MAXIMUM (change from initial) & Discontinuity < 1 microsecond
	Plug Retention Force	Apply an axial pullout force on the plug at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute.	89 N (20 lbf) MINIMUM retention force
	PCB Separation Forces	Apply a perpendicular load on the plug at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute.	4.5 N (1 lbf) MINIMUM withdrawal force before solder reflow 89 N (20 lbf) MINIMUM withdrawal force after solder reflow
	Shock (Mechanical)	Mate connectors and shock at 50 g's with three saw tooth wave form shocks in the ±X,±Y,±Z axis (18 shocks total).	10 milliohms MAXIMUM (change from initial) & Discontinuity < 1 microsecond

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
H2	EC No: UCP2008-0143 DATE: 7/23/2007	PRODUCT SPECIFICATION INVERTED RIGHT ANGLE MODULAR JACKS	3 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43860-003	JBELL 7/23/2007	LSCHMIDT 7/24/2007	FSMITH 7/25/2007



PRODUCT SPECIFICATION

5.3 ENVIRONMENTAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Shock (Thermal)	Mate connectors; expose to 10 cycles of: -40°C to +85°C 30 minutes dwell	10 milliohms MAXIMUM (change from initial) & Visual: No Damage
	Thermal Aging	Mate connectors; expose to: 240 hours at 85±2°C	10 milliohms MAXIMUM (change from initial) & Visual: No Damage
	Humidity (Cyclic)	Mate connectors: expose to 10 cycles at 90-95% relative humidity with temperatures at +25°C and +65°C per MIL-STD-202F method 106F (without -10°C dip)	10 milliohms MAXIMUM (change from initial) & Dielectric Withstanding Voltage: No Breakdown at 500 VAC & Insulation Resistance: 200 Megohms MINIMUM & Visual: No Damage
	Solder Resistance	Dip connector terminal tails in solder: Solder Duration: 7±0.5 seconds Solder Temperature: 260±5°C {Recommended same parameters as SMES-152. } Note: The solder resistance test simulates a wave solder process. This test should not be used to determine the suitability of the connector for a convection or IR reflow solder process.	Visual: No Damage to insulator material

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
H2	EC No: UCP2008-0143 DATE: 7/23/2007	PRODUCT SPECIFICATION INVERTED RIGHT ANGLE MODULAR JACKS	4 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43860-003	JBELL 7/23/2007	LSCHMIDT 7/24/2007	FSMITH 7/25/2007

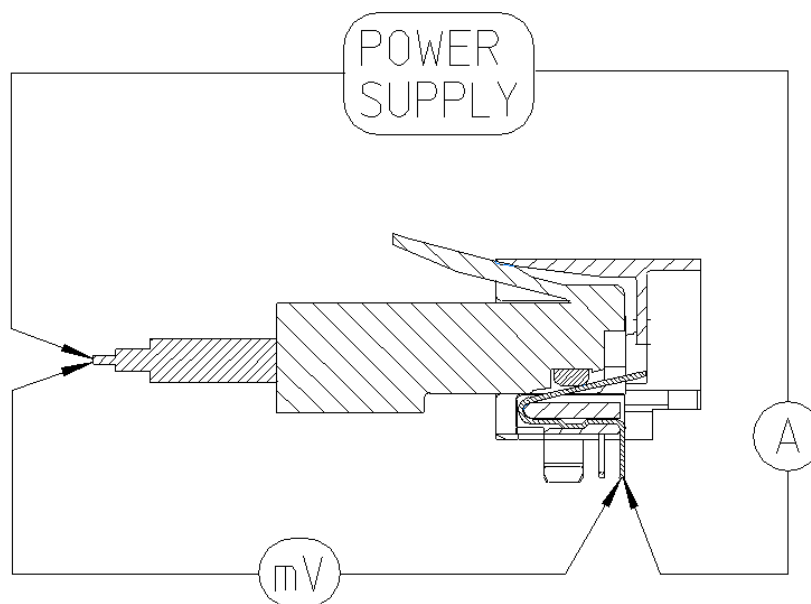


PRODUCT SPECIFICATION

6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage.
See appropriate sales drawings on Sheet 1 for packaging descriptions.

7.0 GAGES AND FIXTURES



TERMINATION RESISTANCE MEASUREMENT POINTS

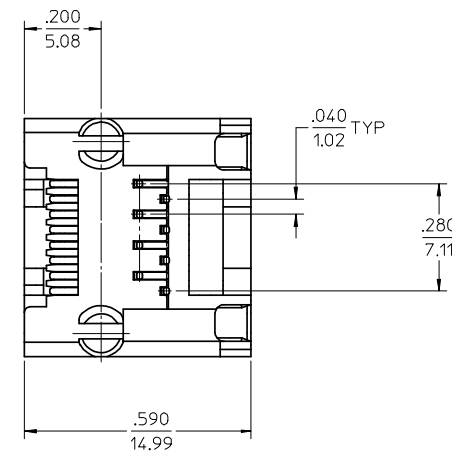
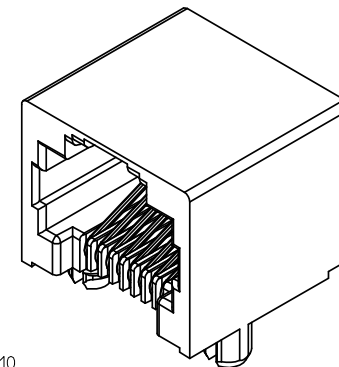
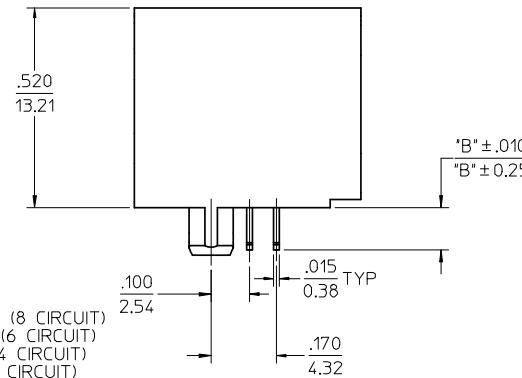
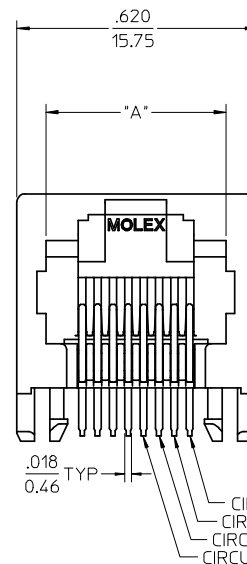
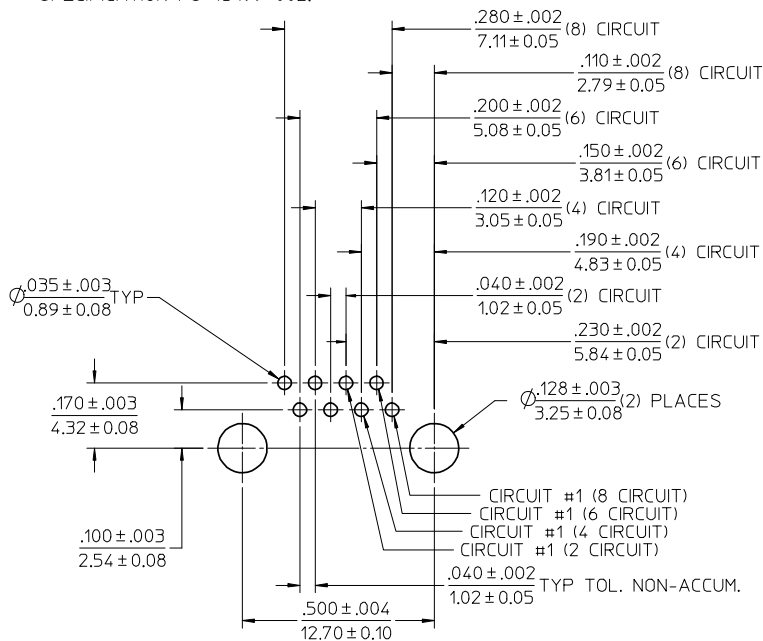
Connector and plug terminals and wire conductor bulk resistance to be subtracted from measurements

8.0 OTHER INFORMATION

REVISION: H2	ECR/ECN INFORMATION: EC No: UCP2008-0143 DATE: 7/23/2007	TITLE: PRODUCT SPECIFICATION INVERTED RIGHT ANGLE MODULAR JACKS	SHEET No. 5 of 5
DOCUMENT NUMBER: PS-43860-003	CREATED / REVISED BY: JBELL 7/23/2007	CHECKED BY: LSCHMIDT 7/24/2007	APPROVED BY: FSMITH 7/25/2007

NOTES:

- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE CHART
TERMINALS: PHOSPHOR BRONZE
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO
RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE
2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT
WITH TIN-LEAD IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX
PACKAGING SPECIFICATION PK-43860-004.
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



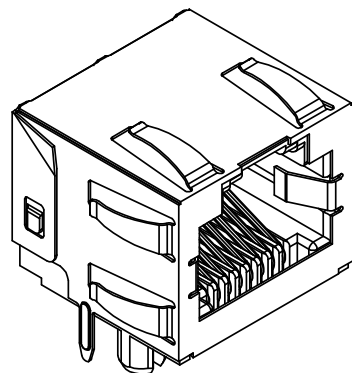
ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	DIM "B"	CIRCUITS	HOUSING COLOR
43860-0001	8	.469/11.91	.110/2.79	8	BLACK
43860-2001	8	.469/11.91	.080/2.03	8	BLACK
43860-0002	6	.389/9.88	.110/2.79	6	BLACK
43860-0003	6	.389/9.88	.110/2.79	4	BLACK
43860-0019	8	.469/11.91	.110/2.79	4	BLACK
43860-0020	6	.389/9.88	.110/2.79	2	BLACK

ADD PART #, SHT 2 EC NO: UCP2008-2146 DRWN:JBELL 2008/03/13 CHKD:ADERR 2008/03/18 APPR:FSM/TH 2008/03/20	DESCRIPTION	QUALITY SYMBOLS
		▽=0 ▽=0
REV		
H5		

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	±.010
2 PLACES ±.25	± ---
1 PLACE ± ---	± ---
ANGULAR ±1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

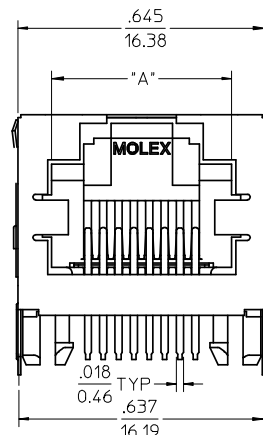
DIMENSION STYLE IN/MM	
DRAWN BY	DATE
TALEND	1997/02/13
CHECKED BY	DATE
ROBERTS	1997/03/03
APPROVED BY	DATE
FRY	1997/03/04
MATERIAL NO.	
SEE CHART	
SIZE	

SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
TITLE INVERTED MODULAR JACK ASSEMBLY		
MOLEX INCORPORATED		
DOCUMENT NO. SD-43860-001		SHEET NO. 1 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

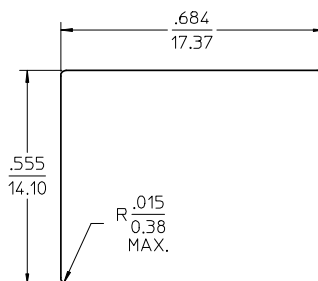


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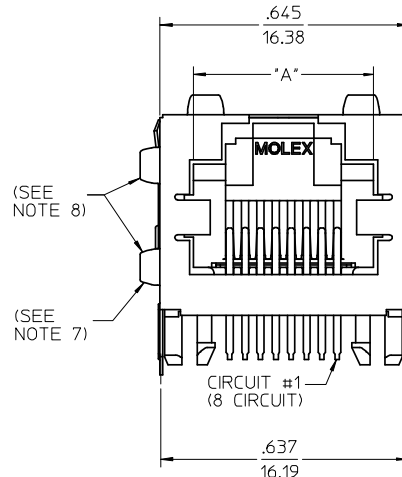
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0,
COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/
1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/
2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/
1.27 MICROMETERS MIN.
SHIELD:
*100 MICROINCHES/2.54 MICROMETERS NICKEL OVER
50 MICROINCHES/1.27 MICROMETERS COPPER
UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED
"COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND
ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN
PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
- 3) PRODUCT SPECIFICATION: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
43860-5025 CONNECTOR ASSEMBLIES PACKAGED IN TAPE AND
REEL PER MOLEX PACKAGING SPECIFICATION PK-70873-700*
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY
MATERIAL NUMBER TABLE.
- 8) AVAILABLE WITH TOP PANEL GROUND TABS ONLY, PER THE
ASSEMBLY MATERIAL NUMBER TABLE.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



NO PANEL
GROUND TABS

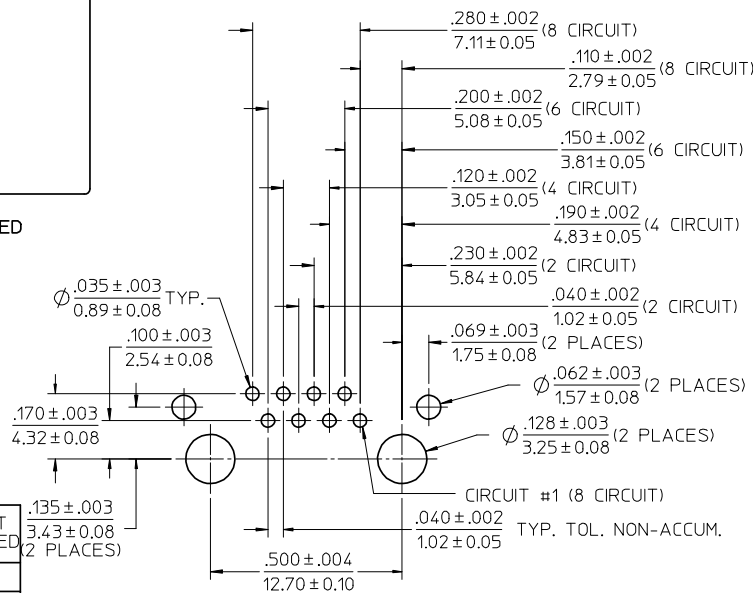
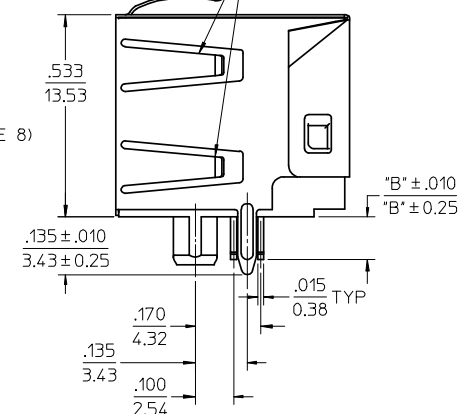


RECOMMENDED
PANEL
OPENING

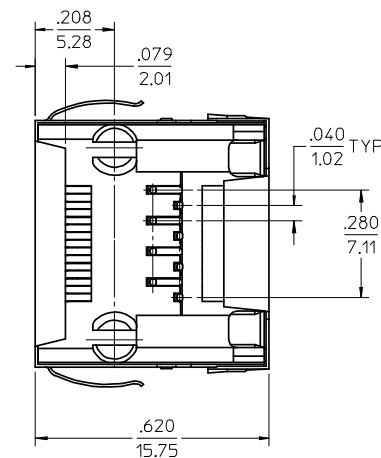


OPTIONAL PANEL
GROUND TAB
(SEE NOTE 7)

PANEL GROUND TABS



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS .062±.005/1.57±.013



ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	DIM "B"	CIRCUITS	PANEL GROUND TABS	PACKAGING OPTION	X=NOT TOOLED
43860-0004	8	.469/11.91	.110/2.79	8	ALL	TRAY	
43860-2004	8	.469/11.91	.080/2.03	8	ALL	TRAY	
43860-0005	6	.389/9.88	.110/2.79	6	ALL	TRAY	
43860-0006	6	.389/9.88	.110/2.79	4	ALL	TRAY	
43860-0013	8	.469/11.91	.110/2.79	8	SEE NOTE #7	TRAY	
43860-0014	6	.389/9.88	.110/2.79	6	SEE NOTE #7	TRAY	
43860-0015	6	.389/9.88	.110/2.79	4	SEE NOTE #7	TRAY	
43860-0024	6	.389/9.88	.110/2.79	2	ALL	TRAY	
43860-0025	8	.469/11.91	.110/2.79	8	NONE	TRAY	
43860-0026	6	.389/9.88	.110/2.79	6	NONE	TRAY	
43860-0027	6	.389/9.88	.110/2.79	4	NONE	TRAY	
43860-0031	8	.469/11.91	.110/2.79	8	SEE NOTE #8	TRAY	
43860-5025	8	.469/11.91	.110/2.79	8	NONE	TAPE	X

ADD 43860-5025
EC NO: UCP2008-2146
DRWN:JBELL 2008/03/13
CHKD:ADERR 2008/03/18
APPR:FSM/TH 2008/03/20
REV DESCRIPTION

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	---	±.010
3 PLACES ±	---	±.010
2 PLACES ±	0.25	±.010
1 PLACE ±	---	±.010

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY	DATE
TALEND	1997/02/13

CHECKED BY	DATE
ROBERTS	1997/03/03

APPROVED BY	DATE
FRY	1997/03/04

MATERIAL NO.
SEE CHART

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE
PROJECTION

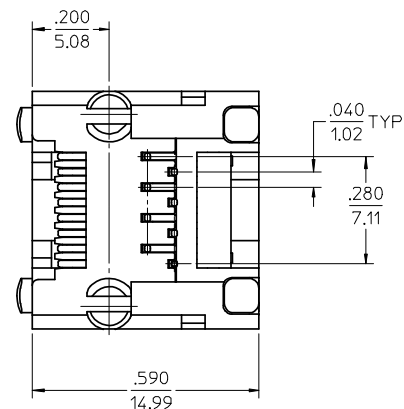
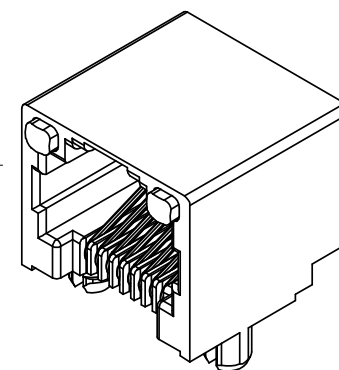
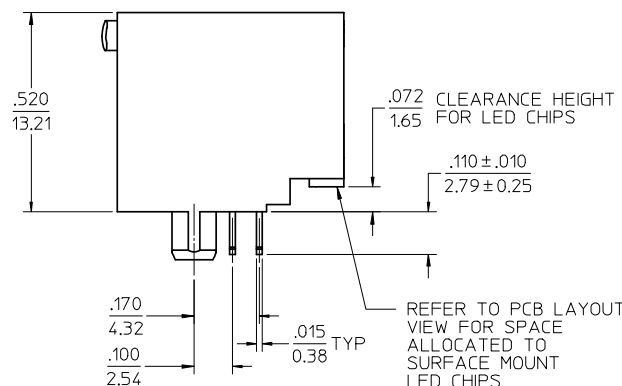
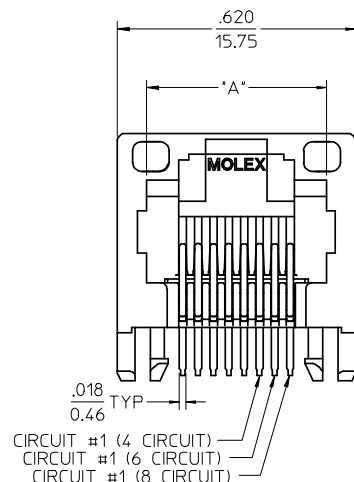
INVERTED MODULAR JACK
ASSEMBLY

MOLEX INCORPORATED

DOCUMENT NO.
SD-43860-001

SHEET NO.
2 OF 5

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK

TERMINALS: PHOSPHOR BRONZE

LIGHT PIPES:

POLYCARBONATE - WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR
CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400°F (205°C)

2) FINISH:

TERMINALS:

SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,

*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,

WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.

*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO
RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE
2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT
WITH TIN-LEAD IN THE PC TAILS.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.

4) PACKAGING SPECIFICATION:

CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX
PACKAGING SPECIFICATION PK-43860-004.

5) APPLICATION SPECIFICATION: AS-43860-001

6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.

8) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.

9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.

ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS
43860-0007	POLYCARBONATE	8	.469/11.91	8
43860-0008	POLYCARBONATE	6	.389/9.88	6
43860-0009	POLYCARBONATE	6	.389/9.88	4
43860-0021	POLYSULFONE	8	.469/11.91	8
43860-0022	POLYSULFONE	6	.389/9.88	6
43860-0023	POLYSULFONE	6	.389/9.88	4

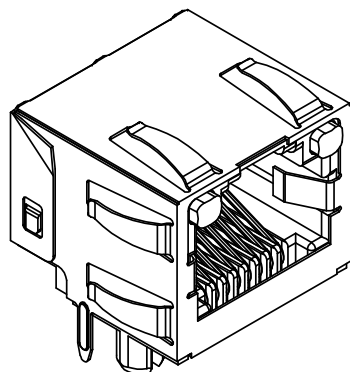
SEE SHEET 1	EC NO: UCP2008-2146	2008/03/13
DRWN:JBELL	2008/03/18	
CHKD:ADERR	2008/03/20	
APPR:FSM1TH		
REV		
H5		

QUALITY SYMBOLS
▽=0
▽=0

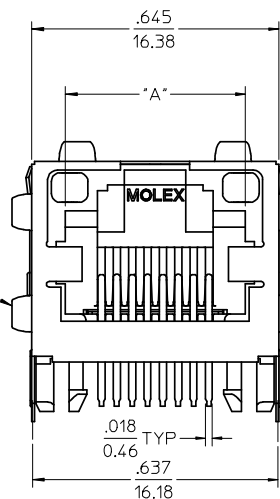
GENERAL TOLERANCES (UNLESS SPECIFIED)
DIMENSION STYLE
IN/MM
mm
INCH
4 PLACES ± --- ± ---
3 PLACES ± --- ± .010
2 PLACES ± 0.25 ± ---
1 PLACE ± --- ± ---
ANGULAR ± 1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DRAWN BY	DATE
TALEND	1997/02/13
CHECKED BY	DATE
ROBERTS	1997/03/03
APPROVED BY	DATE
FRY	1997/03/04
MATERIAL NO.	DOCUMENT NO.
SEE CHART	SD-43860-001
SIZE	
C	

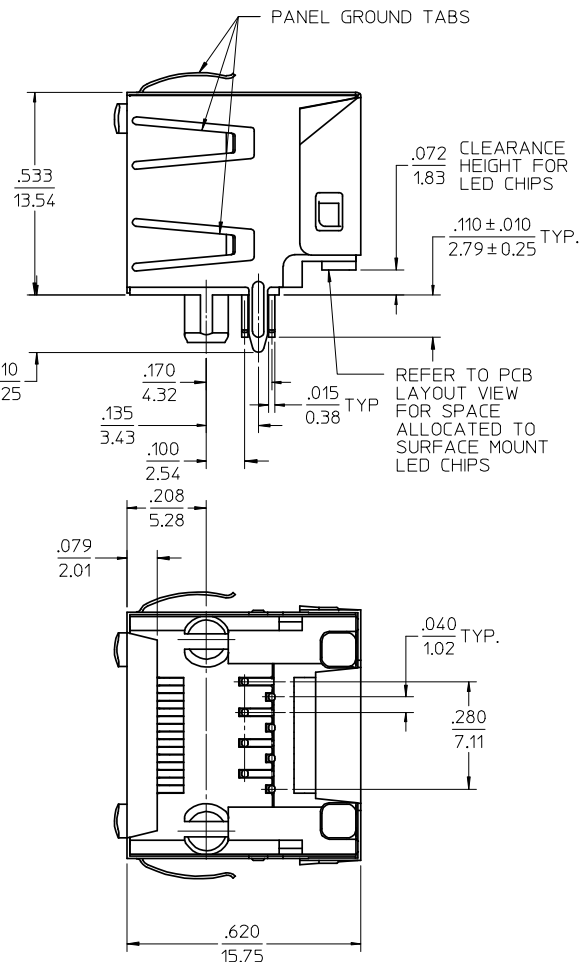
SCALE 4:1	DESIGN UNITS INCH		THIRD ANGLE PROJECTION
TITLE INVERTED MODULAR JACK ASSEMBLY			
MOLEX INCORPORATED			
DOCUMENT NO. SD-43860-001			SHEET NO. 3 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



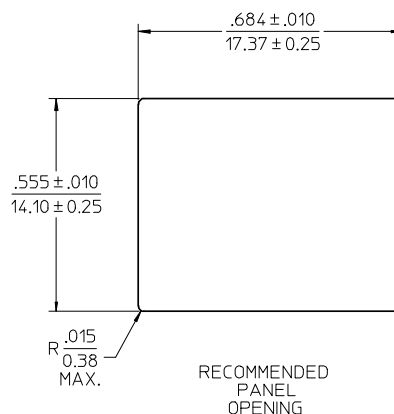
OPTIONAL PANEL
GROUND TAB
(SEE NOTE 8)



OPTIONAL PANEL
GROUND TAB
(SEE NOTE 8)



- NOTES:
- MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
LIGHT PIPES:
POLYCARBONATE - WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR
CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400°F (205°C)
 - FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/1.27 MICROMETERS MIN.
SHIELD:
*100 MICROINCHES/2.54 MICROMETERS OVER 50 MICROINCHES/1.27
MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN
THE PC TAILS AND/OR SHIELD.
 - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX
PACKAGING SPECIFICATION PK-43860-005.
 - APPLICATION SPECIFICATION: AS-43860-001
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE
TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS	PANEL GROUND TABS
43860-0010	POLYCARBONATE	8	.469/11.91	8	ALL
43860-0011	POLYCARBONATE	6	.389/9.88	6	ALL
43860-0012	POLYCARBONATE	6	.389/9.88	4	ALL
43860-0016	POLYCARBONATE	8	.469/11.91	8	SEE NOTE #8
43860-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
43860-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
43860-1010	POLYSULFONE	8	.469/11.91	8	ALL
43860-1011	POLYSULFONE	6	.389/9.88	6	ALL
43860-1012	POLYSULFONE	6	.389/9.88	4	ALL
43860-1016	POLYSULFONE	8	.469/11.91	8	SEE NOTE #8
43860-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
43860-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

SEE SHEET 1
EC NO: UCP2008-2146
DRWN:JBELL 2008/03/13
CHKD:ADERR 2008/03/18
APPR:FSM/TH 2008/03/20
H5

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES ± ---	± ---	± ---
3 PLACES ± ---	± .010	± ---
2 PLACES ± .025	± ---	± ---
1 PLACE ± ---	± ---	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY DATE
TALEND 1997/02/13

CHECKED BY DATE
ROBERTS 1997/03/03

APPROVED BY DATE
FRY 1997/03/04

MATERIAL NO.
SEE CHART

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE
PROJECTION

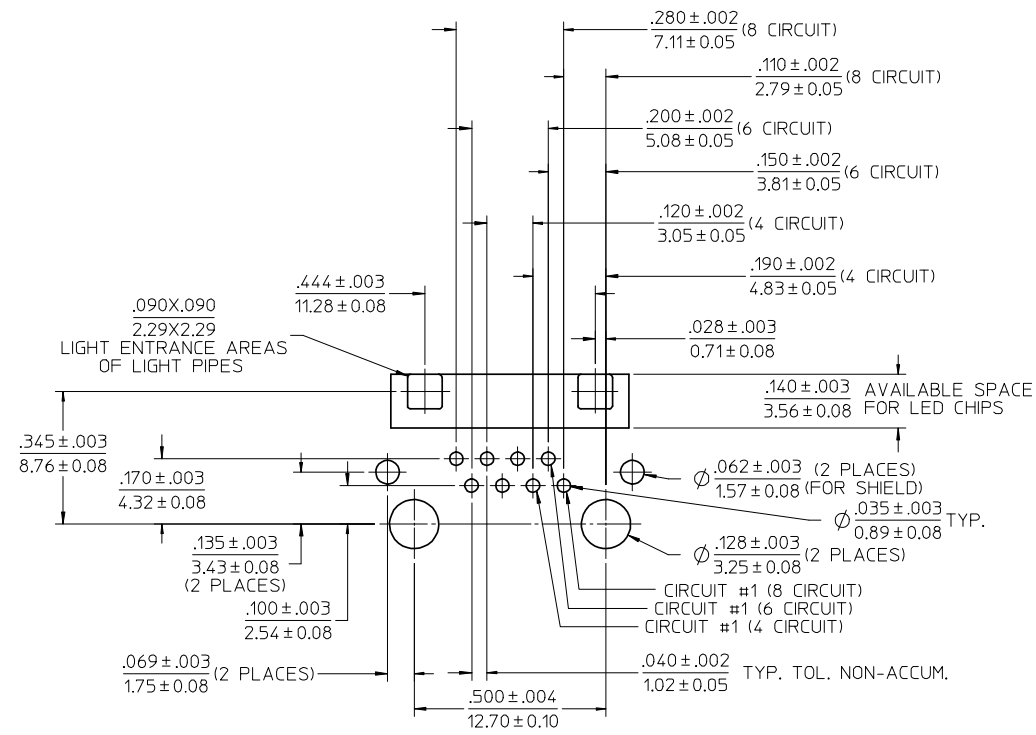
INVERTED MODULAR JACK
ASSEMBLY

MOLEX INCORPORATED

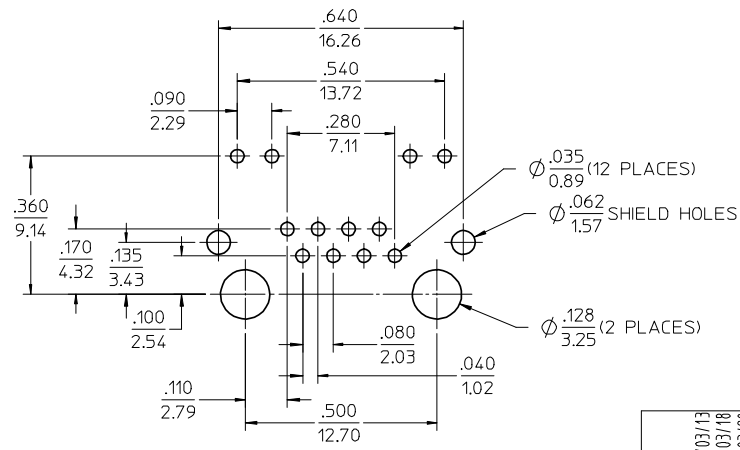
DOCUMENT NO.
SD-43860-001

SHEET NO.
4 OF 5

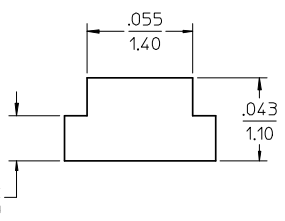
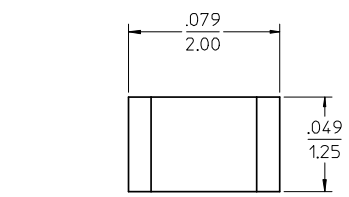
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



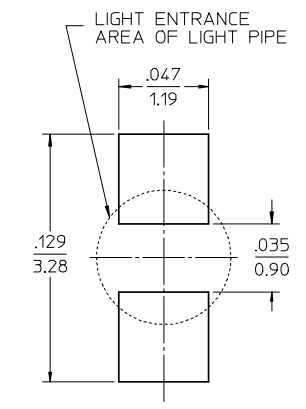
MOLEX RECOMMENDED
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS .062 ± .005/1.57 ± 0.13



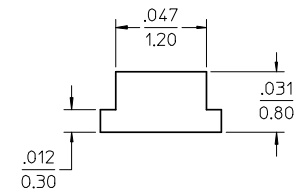
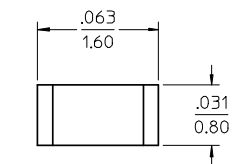
TYPICAL COMPETITION
PCB LAYOUT WITH
INTEGRAL LED'S
(SHOWN FOR REFERENCE ONLY)



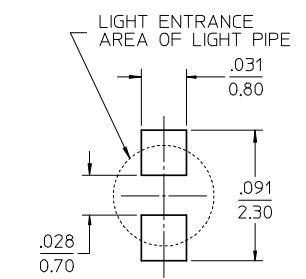
RECOMMENDED SMT
0805 LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)



RECOMMENDED SMT
0805 LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)



RECOMMENDED SMT
0603 LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)



RECOMMENDED SMT
0603 LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)

NOTES:
1. FOR CROSS REFERENCE OF RECOMMENDED LED'S SEE MOLEX WEB SITE

SEE SHEET 1 EC NO: UCP2008-2146 DRWN: BELL 2008/03/13 CHKD: ADERR 2008/03/18 APPR: FSM/TH 2008/03/20 H5	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY TALEND	DATE 1997/02/13	TITLE INVERTED MODULAR JACK ASSEMBLY	
			4 PLACES	± ---	± ---	CHECKED BY ROBERTS	DATE 1997/03/03		
			3 PLACES	± ---	± .010				
			2 PLACES	± 0.25	± ---				
			1 PLACE	± ---	± ---	APPROVED BY FRY	DATE 1997/03/04	 MOLEX INCORPORATED	
			ANGULAR ±1/2°		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-43860-001	SHEET NO. 5 OF 5		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			